

5.1 Introduction

5.2 Equilibrium condition

5.2.1 Contact potential

5.2.2 Equilibrium Fermi level

5.2.3 Space charge at a junction

5.3 Forward- and Reverse-biased junctions; steady state conditions

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5.3.3 Reverse bias

5.4 **Reverse-bias breakdown**

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5.4.4 The breakdown diode

5.4 Reverse Biased Breakdown

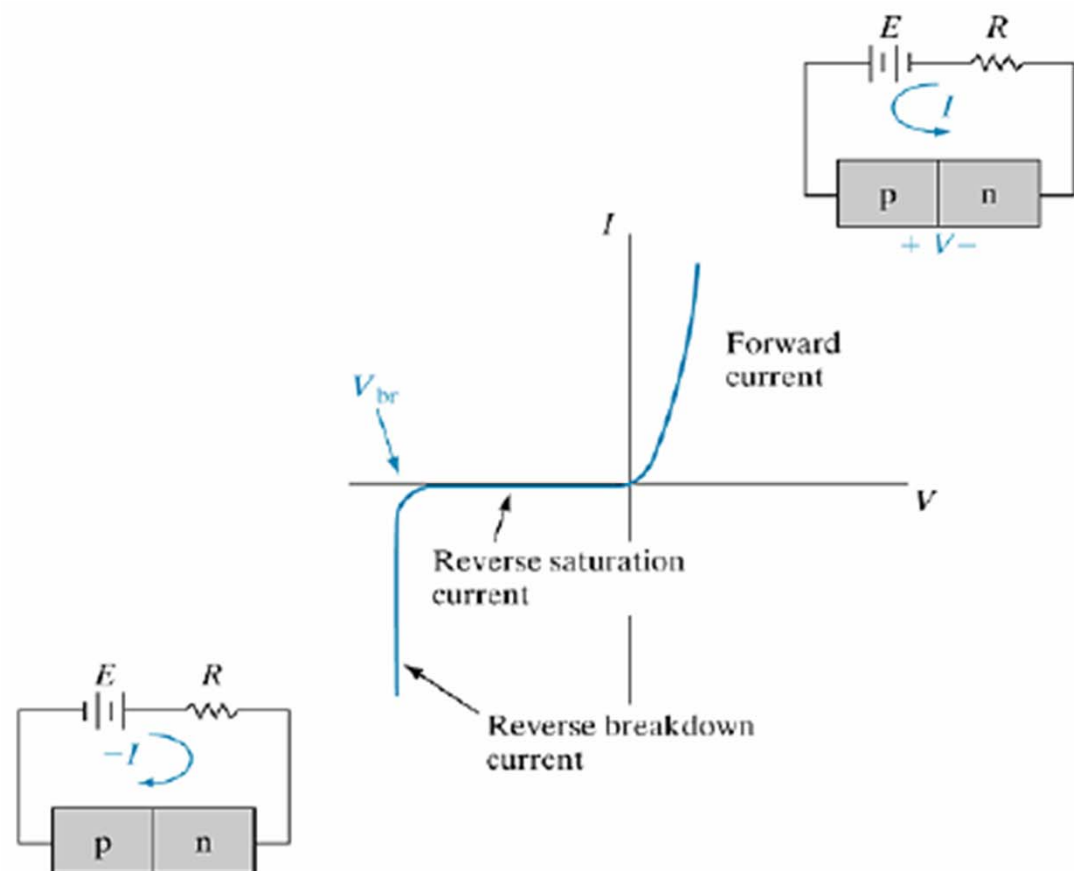
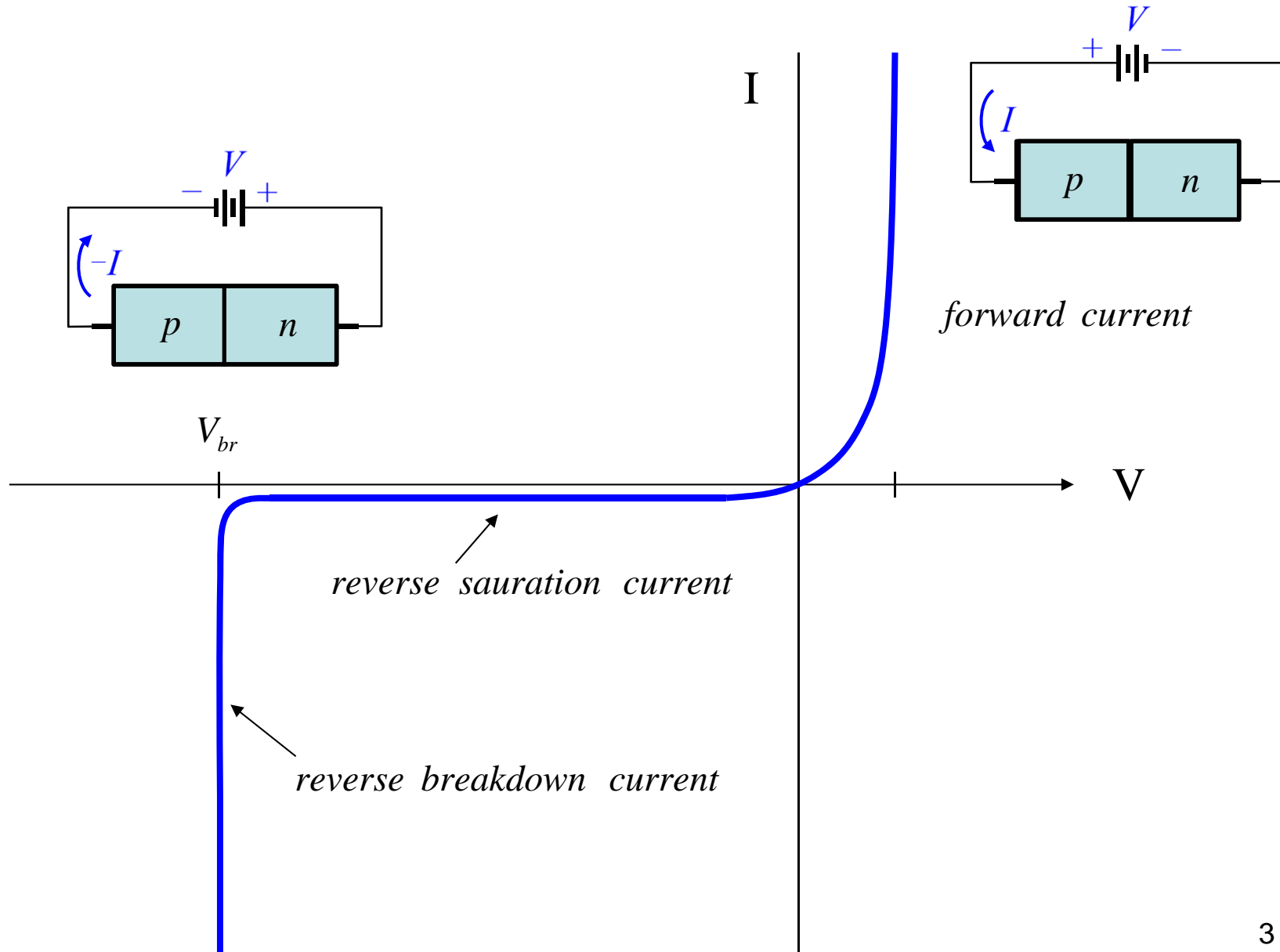


Figure 5—19
Reverse breakdown in a p-n junction.

Reverse Biased Breakdown



5.4.1 Zener Breakdown

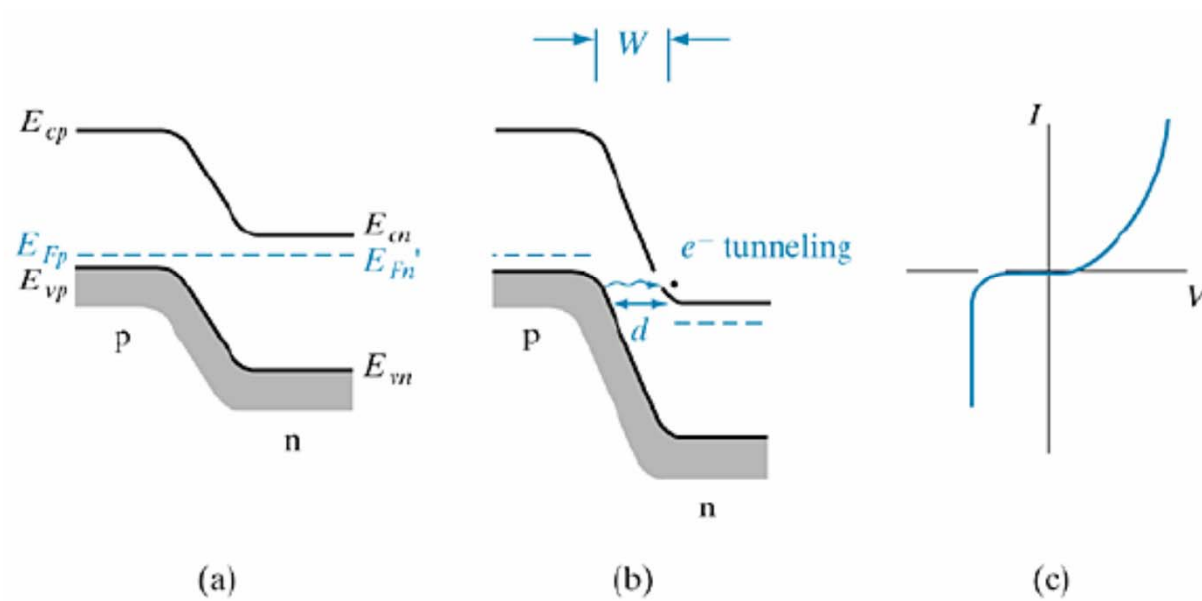
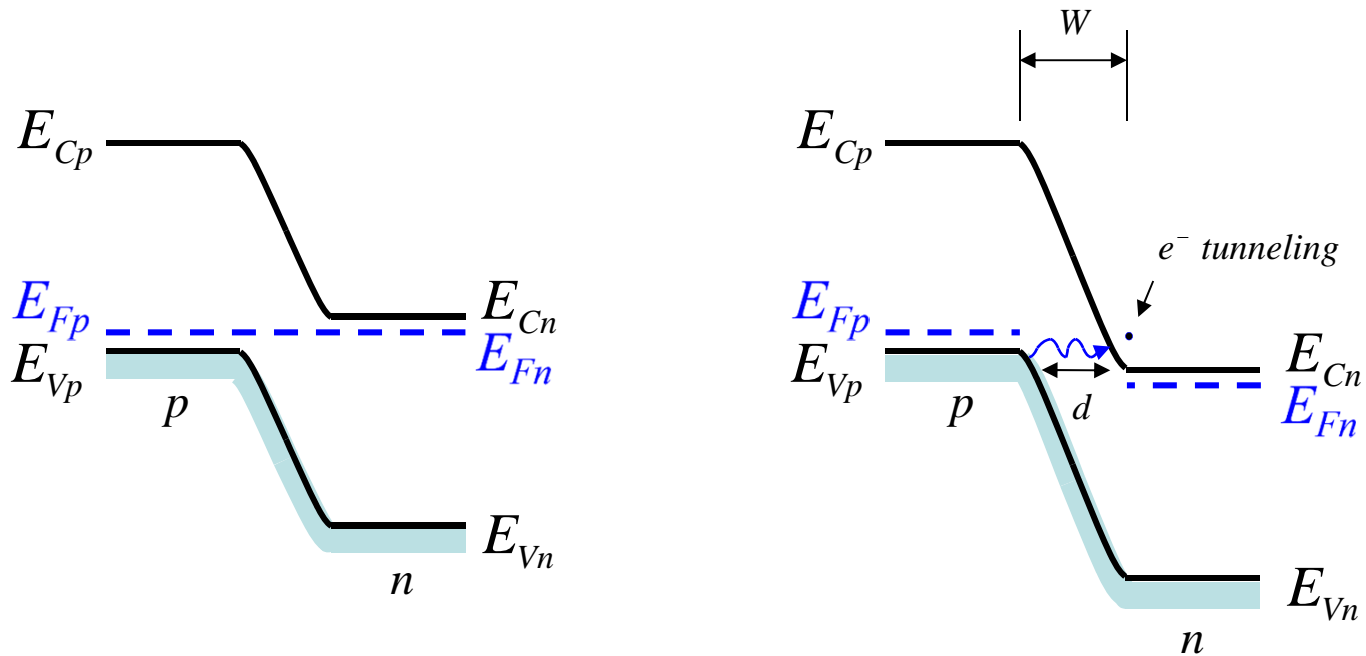


Figure 5—20

The Zener effect: (a) heavily doped junction at equilibrium; (b) reverse bias with electron tunneling from p to n; (c) I - V characteristic.

Zener Breakdown

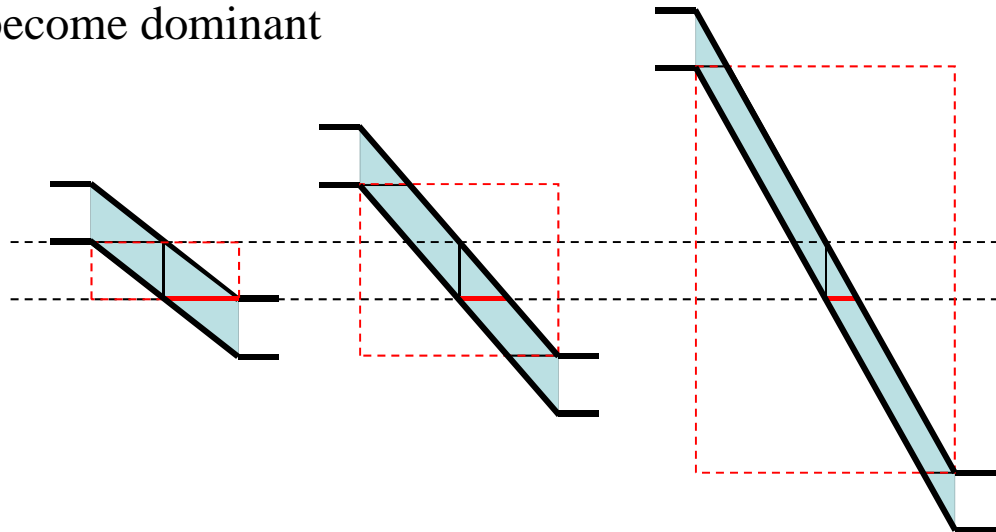


The Zener effect:

- (1) Heavily doped junction at equilibrium,
- (2) Reverse bias with electron tunneling from p to n.

For Zener breakdown (tunneling)

- Extends only a very short distance W from each side of the junction
 - The metallurgical junction be sharp
 - The doping high
- The tunneling distance d may be too large for appreciable tunneling. However,
 - d becomes smaller as the reverse bias is increased, because the higher electric fields result in steeper slopes for the band edges
 - This assumes that the transition region width W does not increase appreciably with reverse bias
 - For low voltages and heavy doping on each side of the junction, this is a good assumption
- If Zener breakdown does not occur with reverse bias of a few volts, avalanche breakdown will become dominant



5.4.2 Avalanche Breakdown

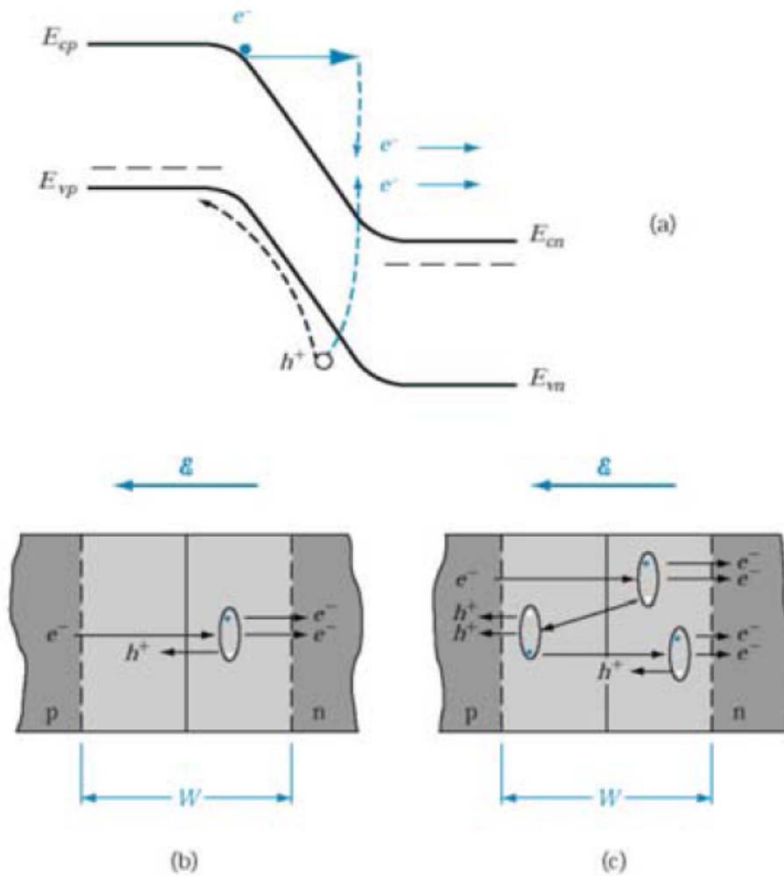
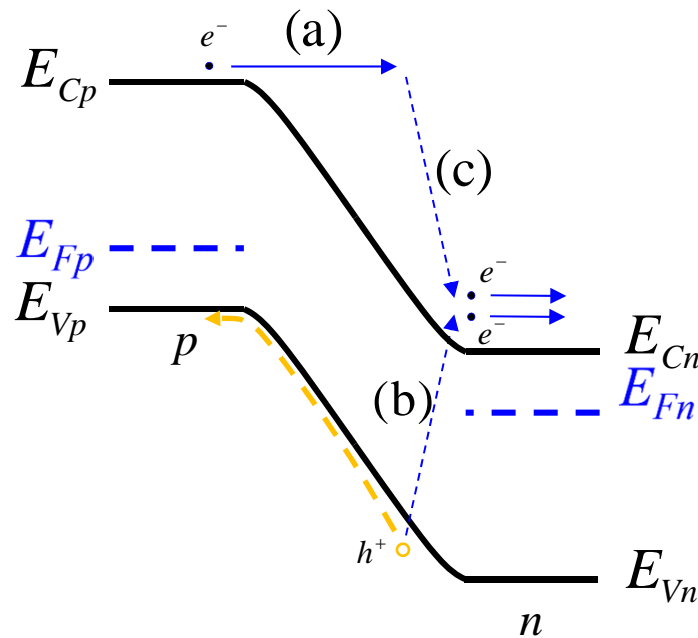


Figure 5-21

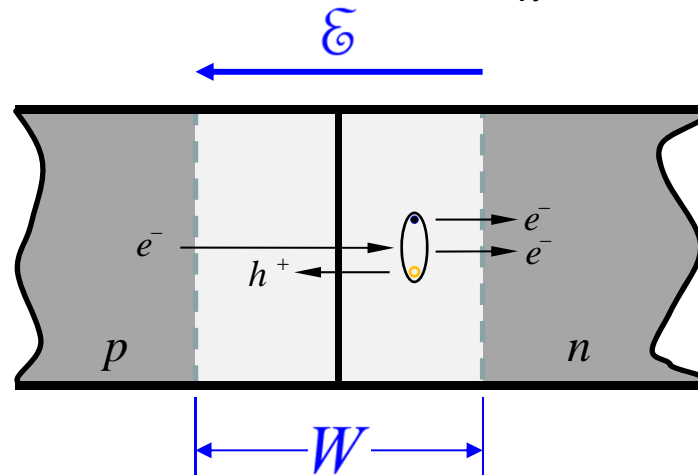
Electron-hole pairs created by impact ionization: (a) band diagram of a p-n junction in reverse bias showing (primary) electron gaining kinetic energy in the field of the depletion region, and creating a (secondary) electron-hole pair by impact ionization, the primary electron losing most of its kinetic energy in the process; (b) a single ionizing collision by an incoming electron in the depletion region of the junction; (c) primary, secondary and tertiary collisions.

Avalanche Breakdown

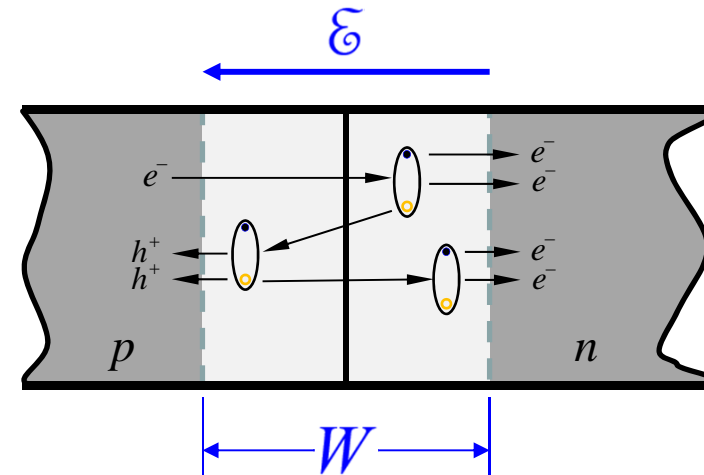


Electron-hole pairs created by impact ionization.

- (a) Electron (primary) gaining kinetic energy in the field of the depletion region.
- (b) An electron-hole pair (secondary) is created by impact ionization.
- (c) The primary electron losing most of its kinetic energy in the process.



A single ionization collision event



Primary, secondary, and tertiary collisions.

Avalanche Breakdown

- In lightly doped junctions electron tunneling is negligible, the breakdown mechanism involves the *impact ionization* of host atoms by energetic carriers.
- A single such interaction results in *carrier multiplication*.

Approximate analysis result:

$$n_{out} = n_{in}(1 + P + P^2 + P^3 + \dots) \quad \text{Assume no recombination}$$

Electron multiplication $M_n = \frac{n_{out}}{n_{in}} = 1 + P + P^2 + P^3 + \dots = \frac{1}{1 - P}$

An empirical relation

$$M = \frac{1}{1 - (V / V_{br})^n} \quad n = 3 \sim 6$$

Avalanche Multiplication

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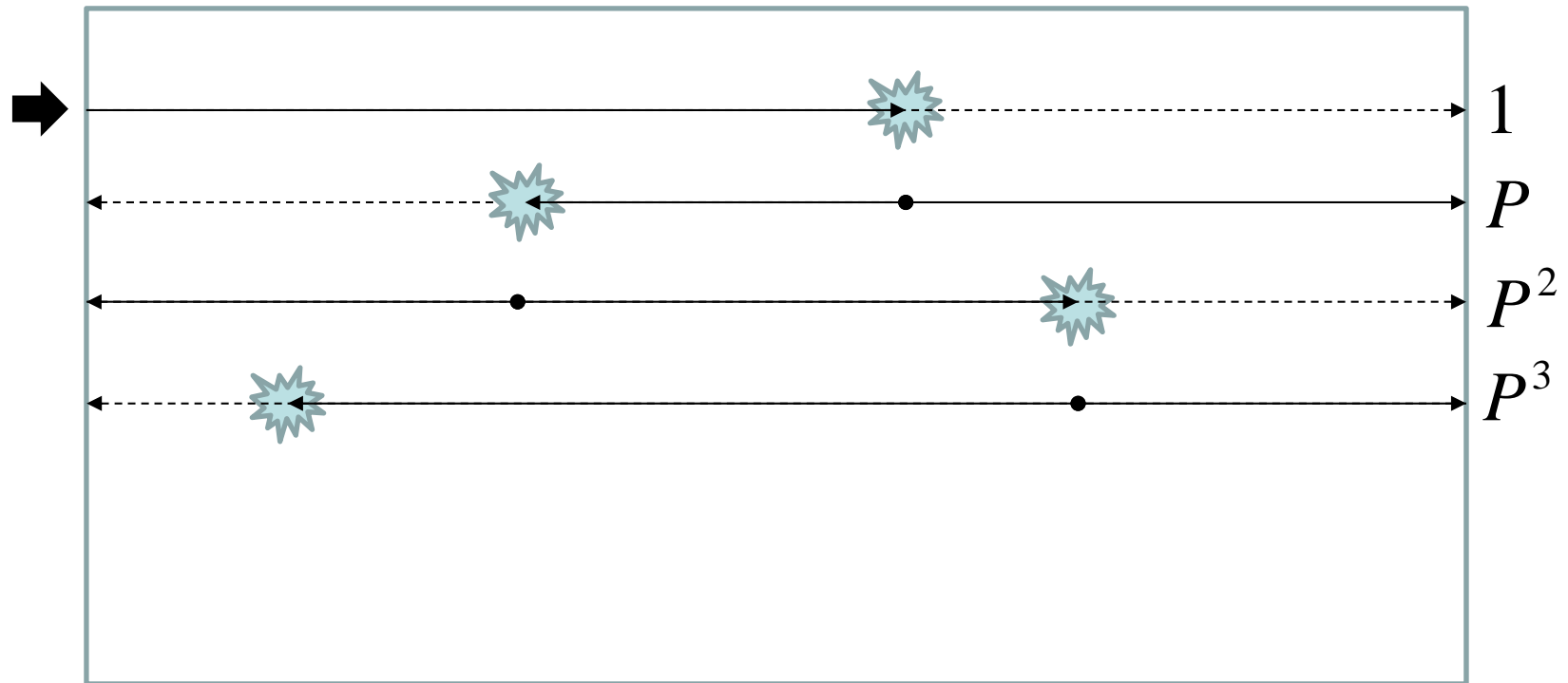
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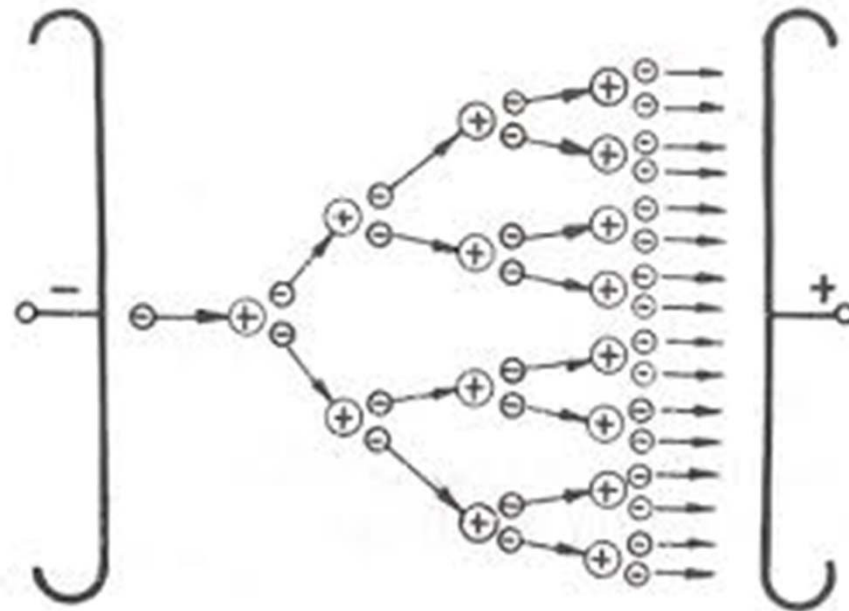
An empirical relation $M = \frac{1}{1 - (\frac{V}{V_{br}})^n} \quad n = 3 \sim 6$

Probability of Ionization P



For Avalanche breakdown

- Impact ionization rather than field ionization (Zener)
- Carrier multiplication
- The peak electric field within W increases with increased doping on the more lightly doped side of the junction (from Eq. 5-23b and Eq. 5-17)



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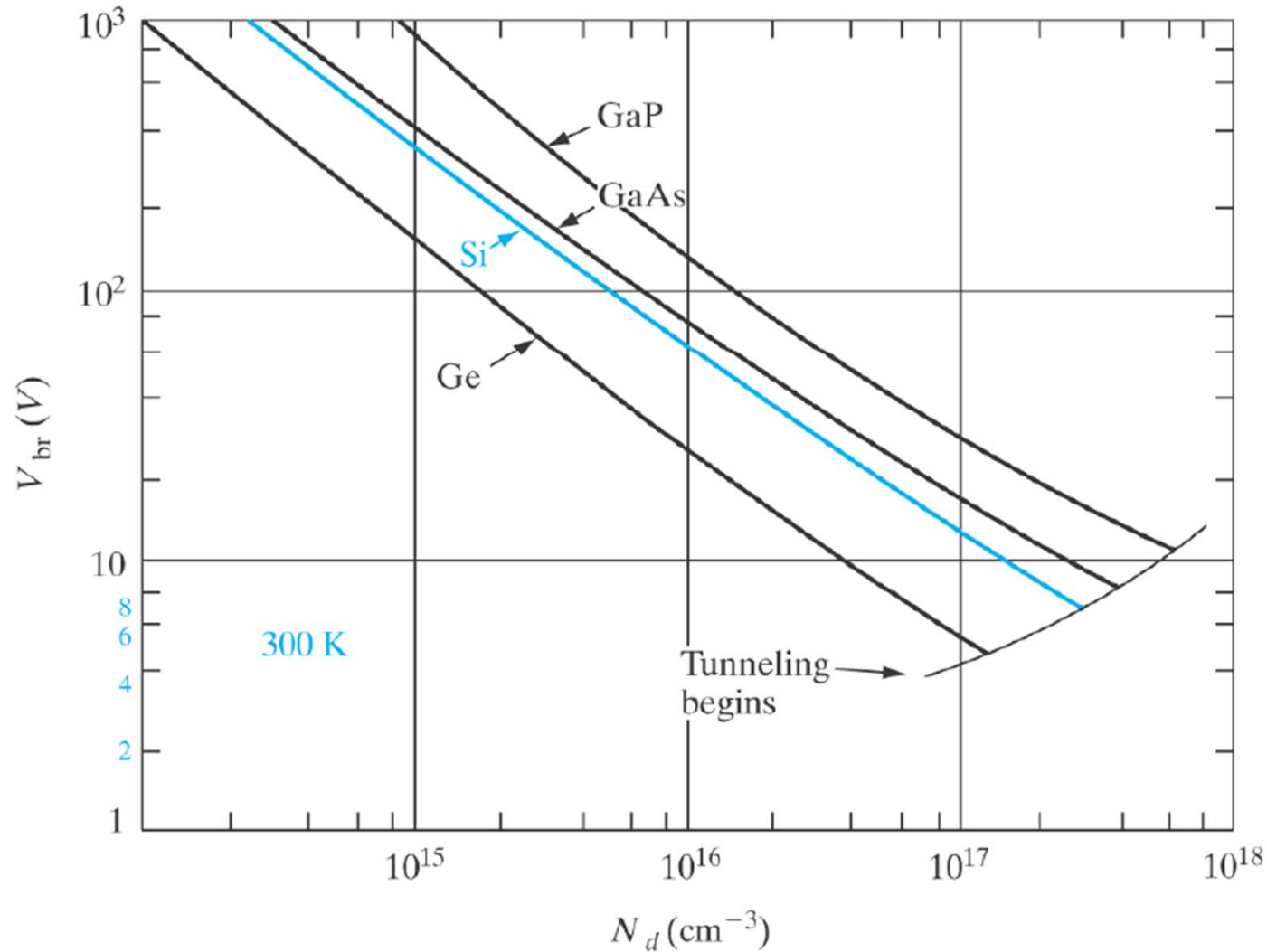


Figure 5—22

Variation of avalanche breakdown voltage in abrupt p^+ - n junctions, as a function of donor concentration on the n side, for several semiconductors. [After S. M. Sze and G. Gibbons, *Applied Physics Letters*, vol. 8, p. 111 (1966).]

Example 5-4

An abrupt Si p-n junction ($A=10^{-4} \text{ cm}^2$) has the following properties at 300 K:

p side

$$N_a = 10^{17} \text{ cm}^{-3}$$

$$\tau_n = 0.1 \mu\text{s}$$

$$\mu_p = 200 \text{ cm}^2 / \text{V} - \text{s}$$

$$\mu_n = 700$$

n side

$$N_d = 10^{15} \text{ cm}^{-3}$$

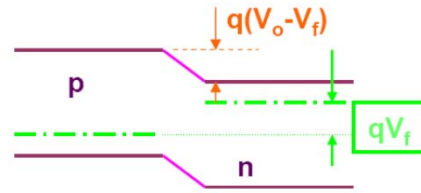
$$\tau_p = 10 \mu\text{s}$$

$$\mu_n = 1300 \text{ cm}^2 / \text{V} - \text{s}$$

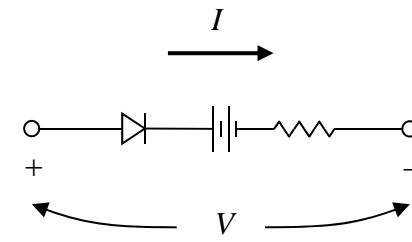
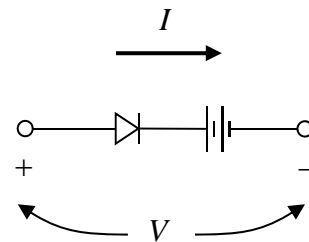
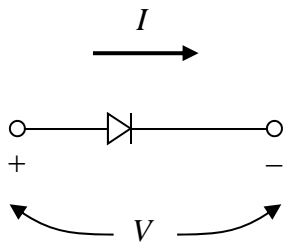
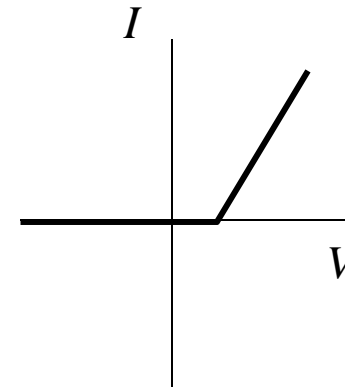
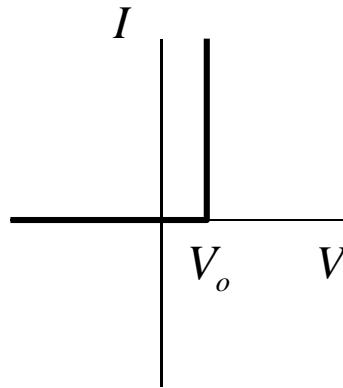
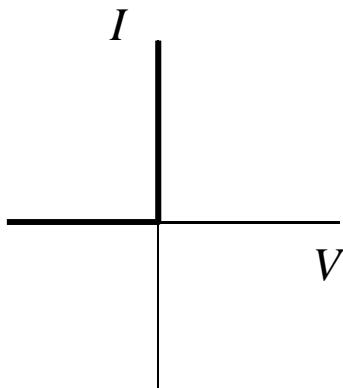
$$\mu_p = 450$$

The junction is forward biased by 0.5 v. What is the forward current? What is the current at a reverse bias of -0.5 V?

5.4.3 Rectifiers



$$V_f \leq V_o \quad \text{always}$$



Consideration for rectifier

Junction diodes designed for use as rectifiers should have I-V characteristics as close as possible to that of the ideal diode.

- The reverse current should be negligible
- The forward current should exhibit little voltage dependence (negligible forward resistance R)
- The reverse breakdown voltage should be large
- The offset voltage E_o in the forward direction should be small.

Large bandgap

- small n_i
 - Small reverse saturation current
- Operable at high temperature
 - Reduced thermal excited EHPs
- Increased contact potential
 - Increased offset voltage E_o

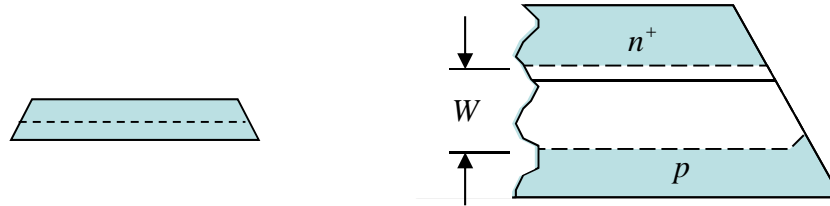
Consideration of doping concentration

The doping concentration on each side of the junction influences the avalanche breakdown voltage, the contact potential, and the series resistance of the diode.

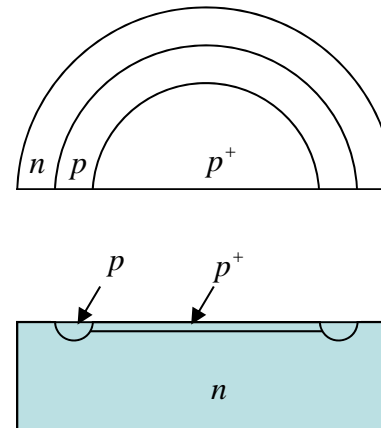
- For p⁺-n junction, the lightly doped region determines many of the properties of the junction.
 - High-resistivity region should be used for at least one side of the junction to increase the breakdown voltage V_{br} .
 - However, this approach tends to increase the forward resistance R
 - Contribute to resistant heating
 - Countermeasure
 - make large area of the lightly doped region
 - The lightly doped region of the junction cannot be made arbitrarily short for punch-through.

Avoid premature breakdown across the edge

- Beveling



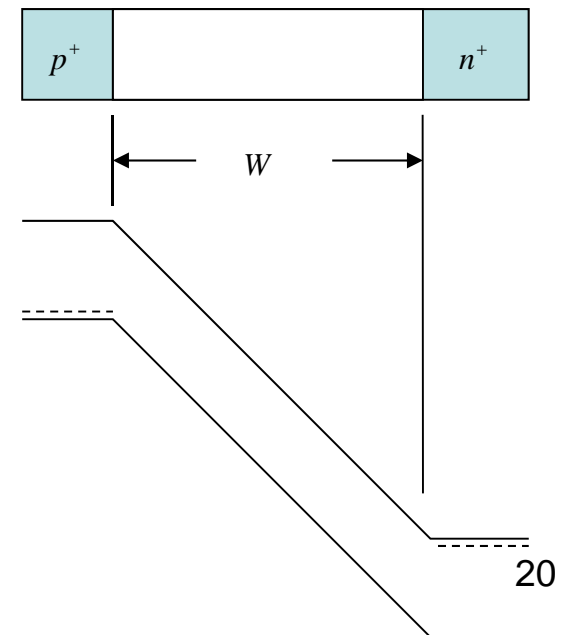
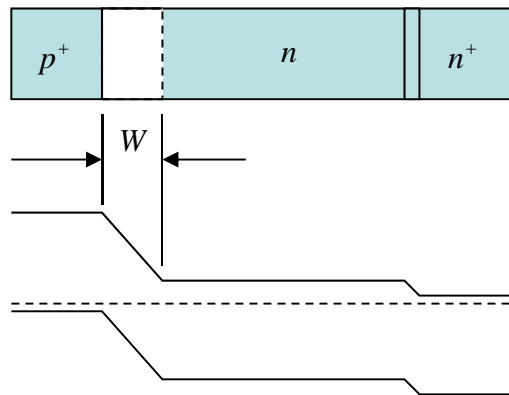
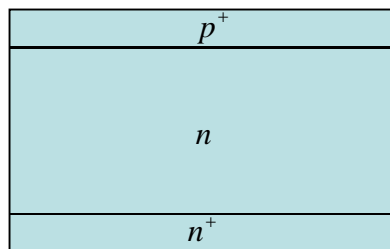
- Guard ring



Consideration of $p^+ - n - n^+$ structure

In fabricating a $p^+ - n$ or $p^+ - n$ junction,

- It is common to terminate the lightly doped region with a heavily doped layer of the same type for ohmic contact to the device
- The result is a $p^+ - n - n^+$ structure with the $p^+ - n$ layer serving as the active junction
 - The lightly doped center region determines the avalanche breakdown voltage
 - If this region is short compared with the minority carrier diffusion length, the excess carrier injection for large forward currents can increase the conductivity of the region significantly
 - This type of *conductivity modulation*, which reduces the forward resistance R , can be very useful for high-current devices
 - On the other hand, a short, lightly doped center region can also lead to punch-through under reverse bias.

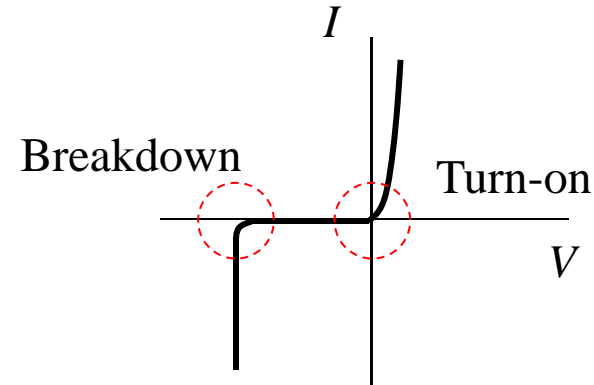


Consideration of Mounting of Rectifier Junction

The mounting of a rectifier junction is critical to its ability to handle power.

- For diodes used in low-power circuits, glass or plastic encapsulation or a simple header mounting is adequate.
- For high current devices, special mountings to transfer thermal energy away from the junction are required.
 - A typical Si power rectifier is mounted on a molybdenum or tungsten disk to match the thermal expansion properties of the Si.
 - This disk is fastened to a large stud of copper or other thermally conductive material that can be bolted to a heat sink.

5.4.4 The breakdown diode



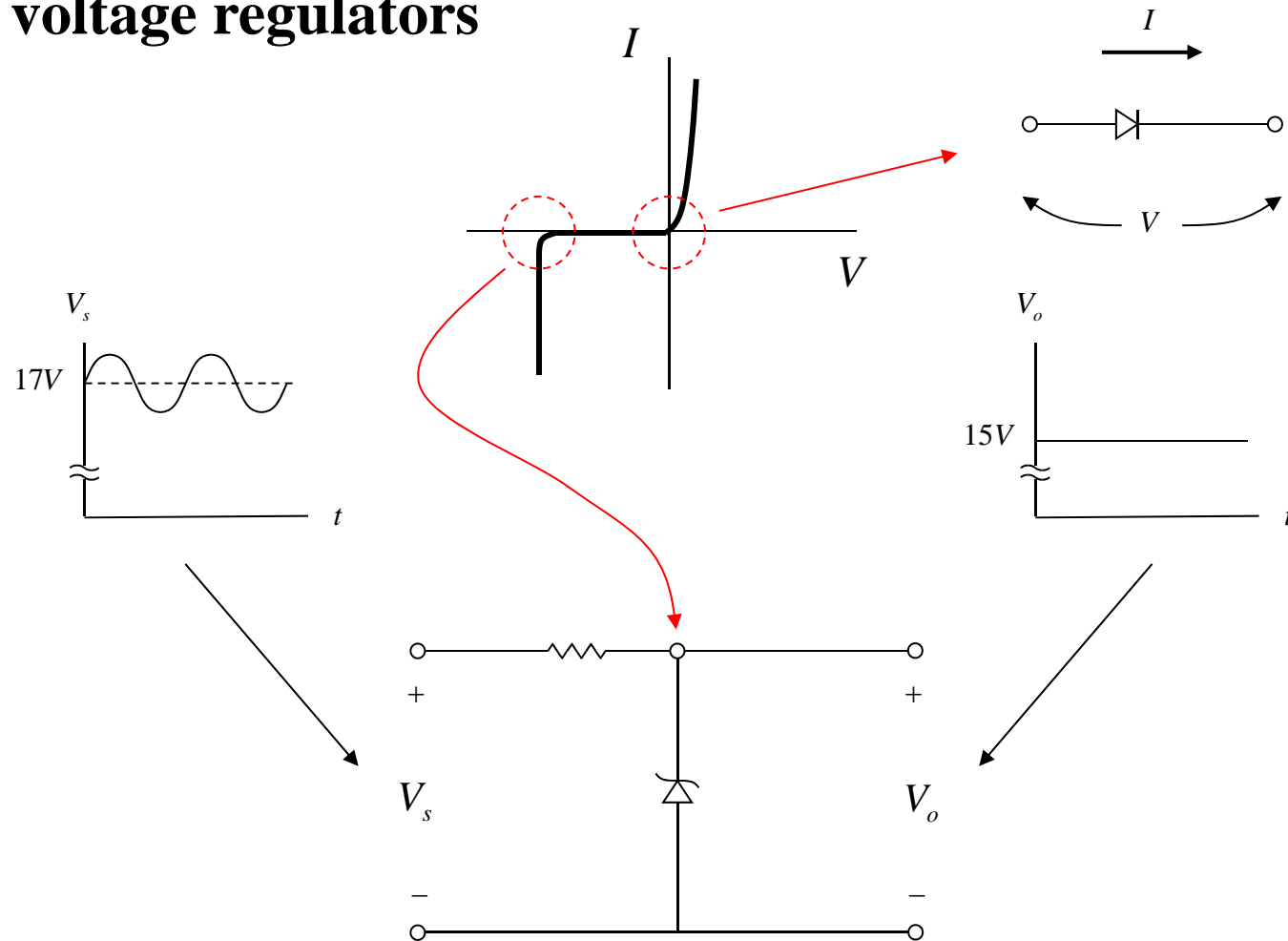
Mechanisms for breakdown

- The Zener effect (tunneling) breakdown mechanism (field ionization) is for abrupt junctions with extremely heavy doping.
- The more common breakdown is avalanche (impact ionization), typically of more lightly doped or graded junctions.

Breakdown \neq material destruction

- There is nothing inherently destructive about reverse breakdown.
- If current is not limited externally, the junction can be damaged by excess reverse current, through overheating.
 - the destruction of the device is not necessarily due to mechanisms unique to reverse breakdown.

The voltage regulators



- When a diode is designed for a specific breakdown voltage, it is called a *breakdown diode*.
- Such diodes are also called *Zener diodes*, despite the fact that the actual breakdown mechanism is usually the avalanche effect.
- Breakdown diodes can be used as *voltage regulators* in circuits with varying inputs.

Voltage Drop across the Diode

$$V_s = i_D R + V_D$$

$$i_D = \frac{V_s - V_D}{R}$$

